


**Features**

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

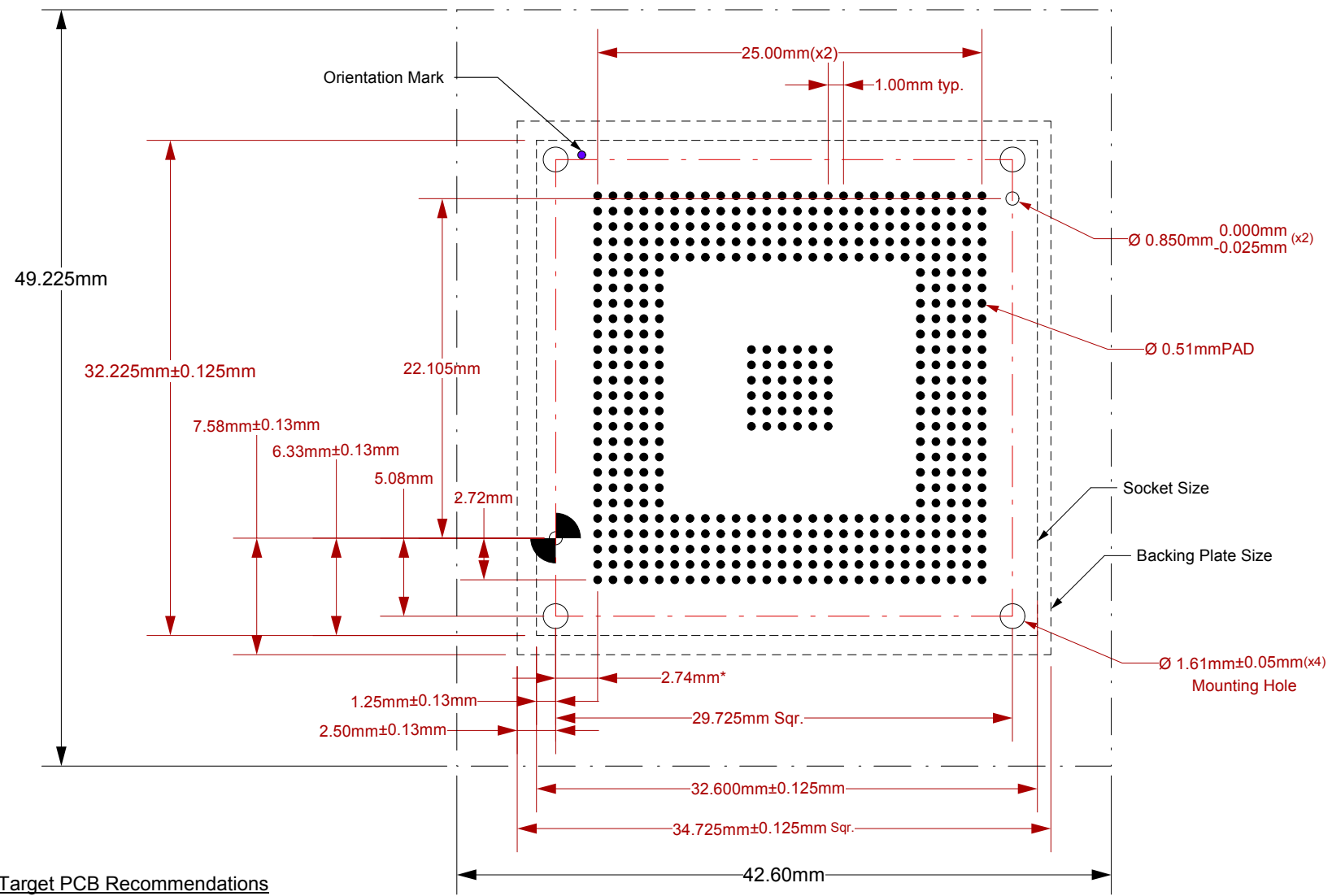
**Materials:**

- 1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- 5 Pogo Pin: Plungers - Hardened Steel/ Gold plated  
Barrel - Copper Alloy/ Gold plated  
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ultem 1000.
- 7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- 8 Backing Plate: Black anodized 7075 Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized 7075 Aluminum.

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.


	<b>SS-BGA456D-02 Drawing</b>	Status: Released	Scale: 1.25:1	Rev: A
	© 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen	Date: 10/19/05	
		File: SS-BGA456D-02 Dwg	Modified:	

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**

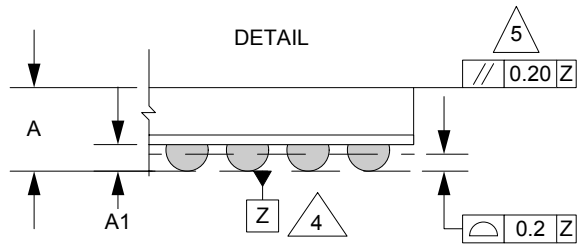
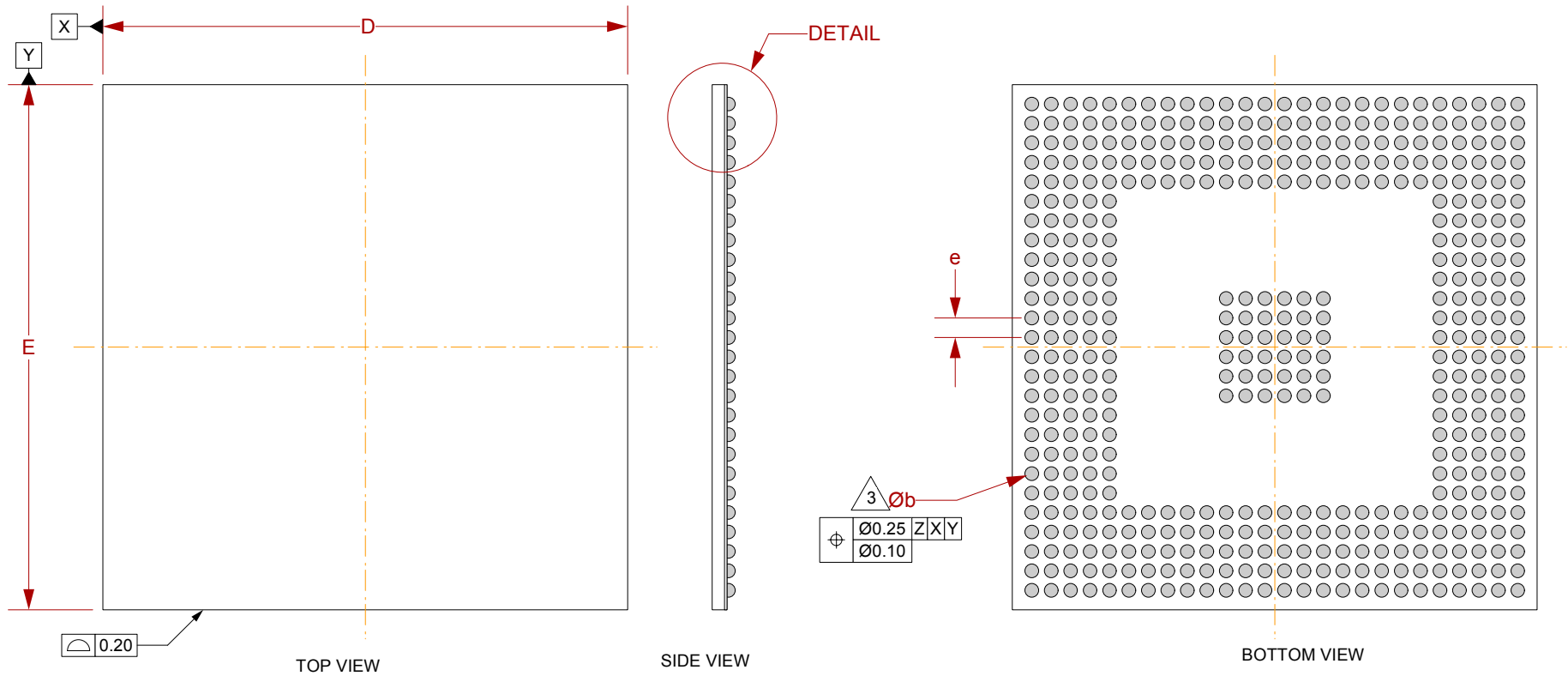


**Target PCB Recommendations**  
Total thickness: 1.5mm min.  
Plating: Gold or Solder finish

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	<b>SS-BGA456D-02 Drawing</b>	Status: Released	Scale: 2.5:1	Rev: A
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		File: SS-BGA456D-02 Dwg	Modified:	


Compatible BGA Spec



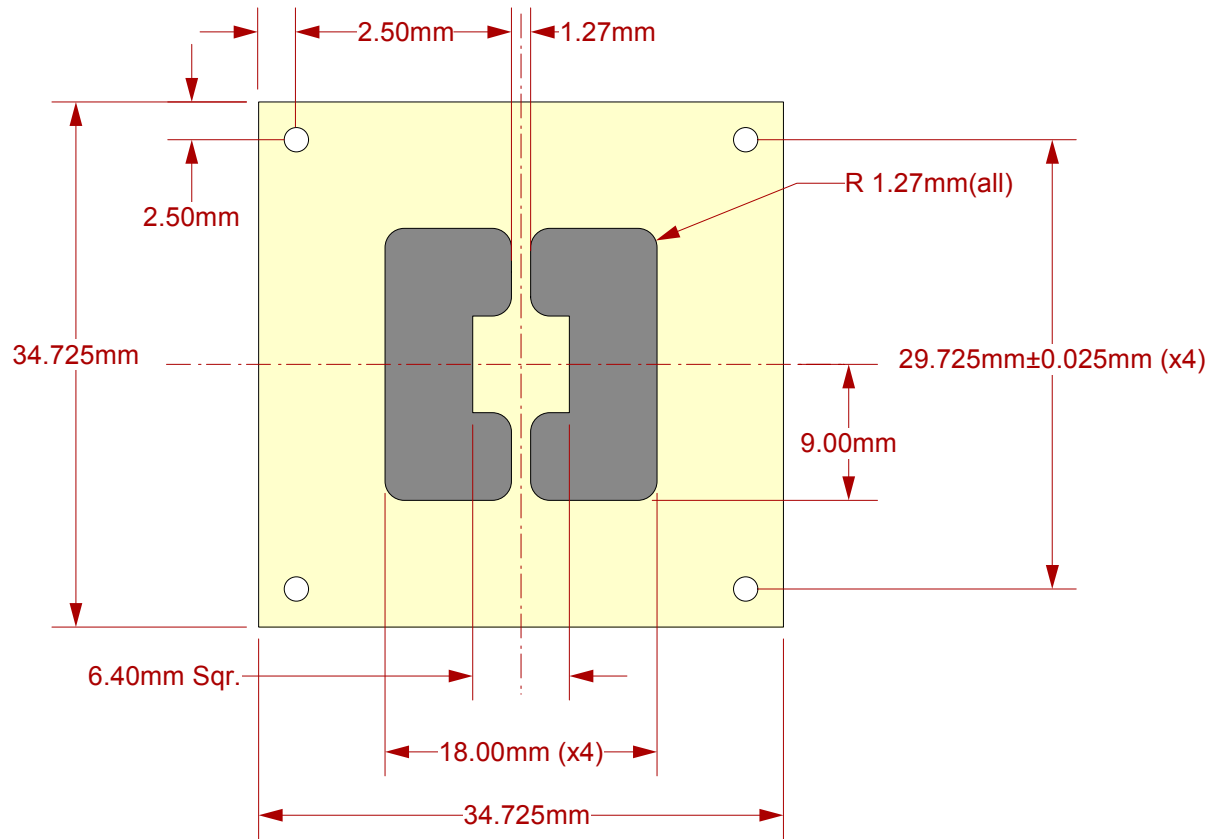
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.4	0.6
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

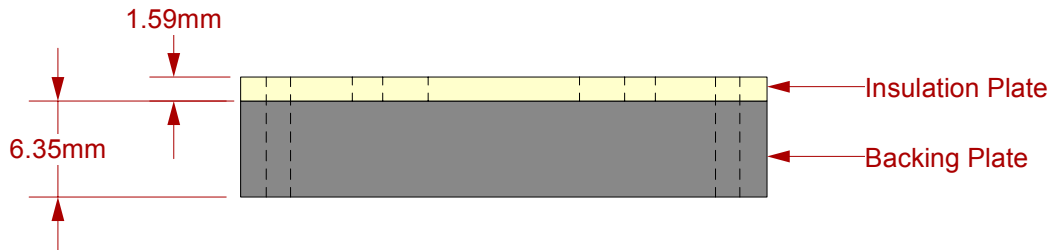
26x26 Array

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Top View



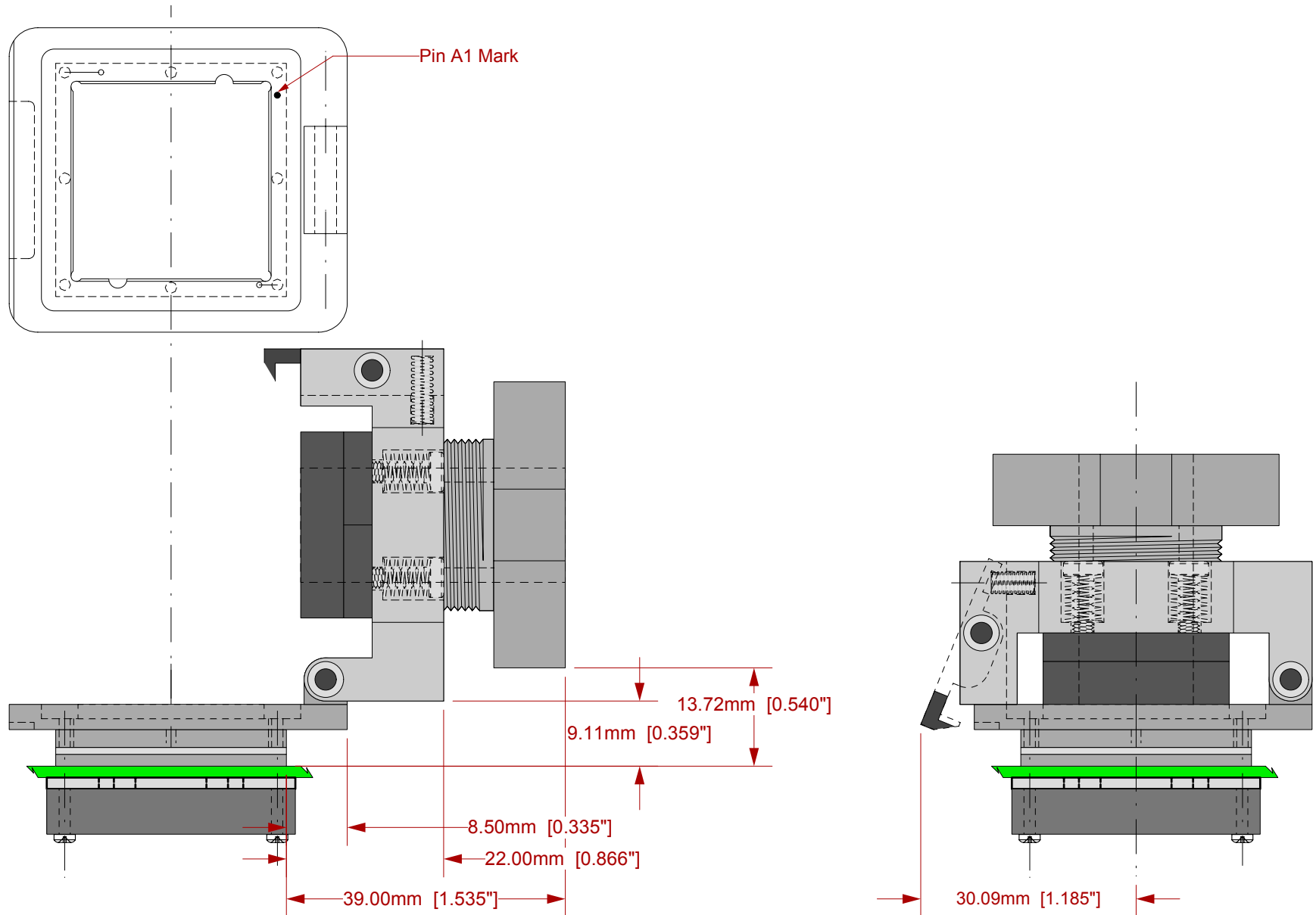
Side View




Description: Backing Plate with Insulation Plate

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		File: SS-BGA456D-02 Dwg	Modified:	

All dimensions are in mm.  
 All tolerances are +/- 0.125mm.  
 (Unless stated otherwise)



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All dimensions are in mm.  
 All tolerances are +/- 0.125mm.  
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